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Title of Invention	DEEP TRENCH FORMATION IN SEMICONDUCTOR DEVICE FABRICATION							
Application Number :								
Date :								
First Named Applicant:	June Cline							
Confirmation Number:								
Attorney Docket Number:	BUR920040122US1							
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<table border="1"><tr><td>Submitted By:</td><td>Elec. Sign.</td><td>Sign. Capacity</td></tr><tr><td>William D. Sabo Registered Number: 27465</td><td>/William D. SABO, Reg 27465/</td><td>Attorney</td></tr></table>			Submitted By:	Elec. Sign.	Sign. Capacity	William D. Sabo Registered Number: 27465	/William D. SABO, Reg 27465/	Attorney
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Documents being submitted:	Files
us-ids	BUR920040122US1-usidst.xml us-ids.dtd us-ids.xsl
us-request	BUR920040122US1-usrequ.xml us-request.dtd us-request.xsl
us-assignment	BUR920040122US1-usassn.xml us-assignment.xsl us-assignment.dtd BUR920040122US1Assign1.tif BUR920040122US1Assign2.tif BUR920040122US1Assign3.tif BUR920040122US1Assign4.tif
us-fee-sheet	BUR920040122US1-usfees.xml us-fee-sheet.xsl us-fee-sheet.dtd
us-declaration	BUR920040122US1DEC3.tif
application-body	BUR920040122appABX.xml application-body.dtd Image1.tif Image2.tif Image3.tif Image4.tif Image5.tif Image6.tif Image7.tif isoamsa.ent isoamsb.ent isoamsc.ent isoamsn.ent isoamso.ent isoamsr.ent isobox.ent isocyr1.ent isocyr2.ent isodia.ent isogr1.ent isogr2.ent isogr3.ent isogr4.ent isolat1.ent isolat2.ent isomfrk.ent isomopf.ent isomscr.ent isonum.ent isopub.ent isotech.ent mathml2.dtd

	mathml2-qname-1.mod
	mmlalias.ent
	mmlextra.ent
	soextblx.dtd
	us-application-body.xsl
	wipo.ent
application-body-pdf-wrap	BUR920040122appABX-pdf-wrap.xml
abstract-pdf	BUR920040122appABX-abst.pdf
claims-pdf	BUR920040122appABX-clms.pdf
description-pdf	BUR920040122appABX-desc.pdf
drawings-pdf	BUR920040122appABX-draw.pdf
us-declaration	BUR920040122US1DEC1.tif
us-declaration	BUR920040122US1DEC2.tif
Comments	
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